

**P-Channel Enhancement Mode Power MOSFET**

# MTB032P06AV8

BV <sub>DSS</sub>	-60V
I <sub>D</sub> @V <sub>GS</sub> =-10V, T <sub>C</sub> =25°C	-25A
R <sub>DS(on)</sub> @V <sub>GS</sub> =10V, I <sub>D</sub> =-6A	30mΩ (typ)
R <sub>DS(on)</sub> @V <sub>GS</sub> =-4.5V, I <sub>D</sub> =-4A	35mΩ (typ)

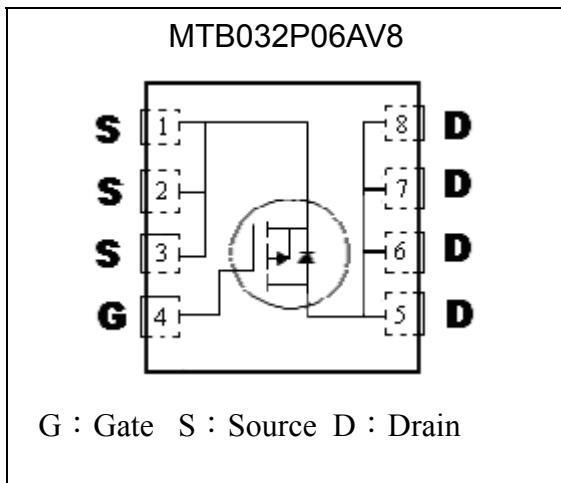
**Description**

The MTB032P06AV8 is a P-channel enhancement-mode MOSFET, providing the designer with the best combination of fast switching, ruggedized device design, low on-resistance and cost effectiveness.

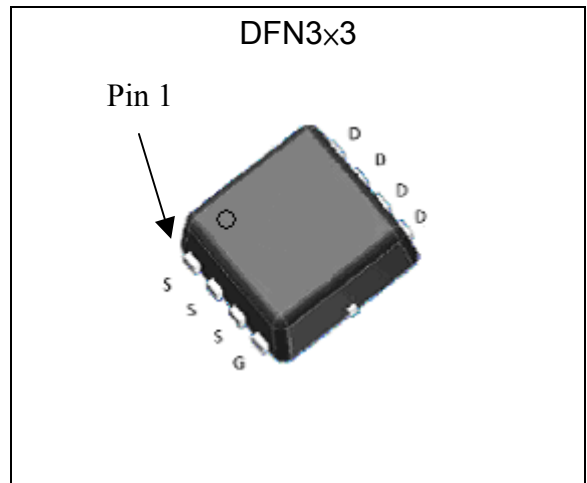
**Features**

- Simple drive requirement
- Low on-resistance
- Fast switching speed
- Pb-free lead plating and halogen-free package

**Equivalent Circuit**

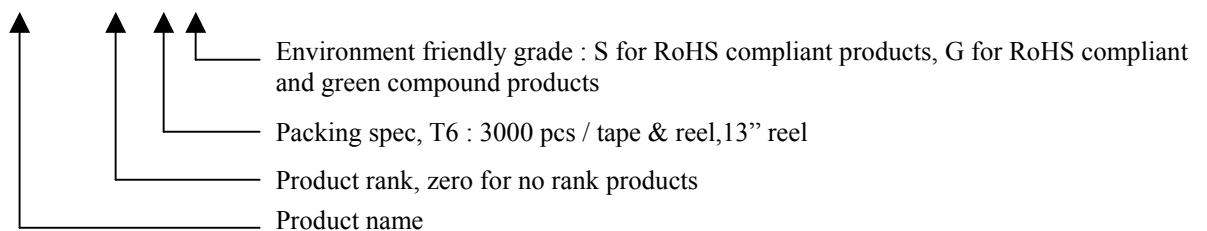


**Outline**



**Ordering Information**

Device	Package	Shipping
MTB032P06AV8-0-T6-G	DFN3x3 (Pb-free lead plating and halogen-free package)	3000 pcs / Tape & Reel





**Absolute Maximum Ratings (Ta=25°C)**

Parameter	Symbol	Limits	Unit	
Drain-Source Voltage	V <sub>DS</sub>	-60	V	
Gate-Source Voltage	V <sub>GS</sub>	±25		
Continuous Drain Current @ T <sub>C</sub> =25°C, V <sub>GS</sub> =-10V	I <sub>D</sub>	-25	A	
Continuous Drain Current @ T <sub>C</sub> =100°C, V <sub>GS</sub> =-10V		-16		
Continuous Drain Current @ T <sub>A</sub> =25°C, V <sub>GS</sub> =-10V		-6.6		
Continuous Drain Current @ T <sub>A</sub> =70°C, V <sub>GS</sub> =-10V		-5.3		
Pulsed Drain Current	I <sub>DM</sub>	-40 *1		
Avalanche Current	I <sub>AS</sub>	-10		
Avalanche Energy @ L=0.1mH, I <sub>D</sub> =-10A, R <sub>G</sub> =25Ω	E <sub>AS</sub>	5	mJ	
Repetitive Avalanche Energy @ L=0.05mH	E <sub>AR</sub>	2.5 *2		
Total Power Dissipation	P <sub>D</sub>	T <sub>C</sub> =25°C	36	W
		T <sub>C</sub> =100°C	14	
		T <sub>A</sub> =25°C	2.5 *3	
		T <sub>A</sub> =70°C	1.6 *3	
Operating Junction and Storage Temperature Range	T <sub>j</sub> , T <sub>stg</sub>	-55~+150	°C	

**Thermal Data**

Parameter	Symbol	Value	Unit
Thermal Resistance, Junction-to-case, max	R <sub>th,j-c</sub>	3.5	°C/W
Thermal Resistance, Junction-to-ambient, max	R <sub>th,j-a</sub>	50 *3	

- Note : 1. Pulse width limited by maximum junction temperature  
 2. Duty cycle ≤ 1%  
 3. Surface mounted on 1 in<sup>2</sup> copper pad of FR-4 board, t ≤ 10s ; 125°C/W when mounted on minimum copper pad.

**Electrical Characteristics (T<sub>j</sub>=25°C, unless otherwise specified)**

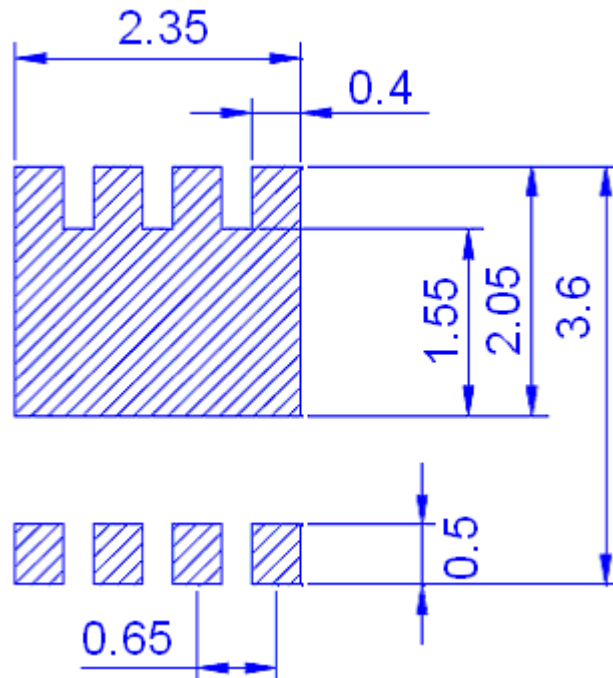
Symbol	Min.	Typ.	Max.	Unit	Test Conditions
<b>Static</b>					
BV <sub>DSS</sub>	-60	-	-	V	V <sub>GS</sub> =0V, I <sub>D</sub> =-250μA
V <sub>GS(th)</sub>	-0.8	-	-2.5		V <sub>DS</sub> =V <sub>GS</sub> , I <sub>D</sub> =-250μA
I <sub>GSS</sub>	-	-	±100	nA	V <sub>GS</sub> =±25V, V <sub>DS</sub> =0V
I <sub>DSS</sub>	-	-	-1	μA	V <sub>DS</sub> =-48V, V <sub>GS</sub> =0V
	-	-	-25		V <sub>DS</sub> =-48V, V <sub>GS</sub> =0V, T <sub>j</sub> =125°C
R <sub>DS(ON)</sub> *1	-	30	39	mΩ	V <sub>GS</sub> =-10V, I <sub>D</sub> =-6A
	-	35	46		V <sub>GS</sub> =-4.5V, I <sub>D</sub> =-4A
G <sub>FS</sub> *1	-	18	-	S	V <sub>DS</sub> =-5V, I <sub>D</sub> =-6A
<b>Dynamic</b>					
C <sub>iss</sub>	-	2827	-	pF	V <sub>DS</sub> =-30V, V <sub>GS</sub> =0V, f=1MHz
C <sub>oss</sub>	-	109	-		
C <sub>rss</sub>	-	70	-		

**Electrical Characteristics(Cont.)** (Tj=25°C, unless otherwise specified)

Symbol	Min.	Typ.	Max.	Unit	Test Conditions
t <sub>d(ON)</sub> *1, 2	-	18	-	ns	V <sub>DS</sub> =-30V, I <sub>D</sub> =-6A, V <sub>GS</sub> =-10V, R <sub>G</sub> =6Ω
t <sub>r</sub> *1, 2	-	12	-		
t <sub>d(OFF)</sub> *1, 2	-	99	-		
t <sub>f</sub> *1, 2	-	35	-		
Q <sub>g</sub> *1, 2	-	32	-	nC	V <sub>DS</sub> =-48V, I <sub>D</sub> =-6A, V <sub>GS</sub> =-10V
Q <sub>gs</sub> *1, 2	-	8	-		
Q <sub>gd</sub> *1, 2	-	10	-		
<b>Source-Drain Diode</b>					
V <sub>SD</sub> *1	-	-0.74	-1	V	I <sub>S</sub> =-3A, V <sub>GS</sub> =0V
t <sub>rr</sub>	-	75	-	ns	I <sub>F</sub> =6A, dI <sub>F</sub> /dt=100A/μs
Q <sub>rr</sub>	-	98	-	nC	

Note : \*1.Pulse Test : Pulse Width ≤300μs, Duty Cycle≤2%  
 \*2.Independent of operating temperature  
 \*3.Pulse width limited by maximum junction temperature.

**Recommended Soldering Footprint**

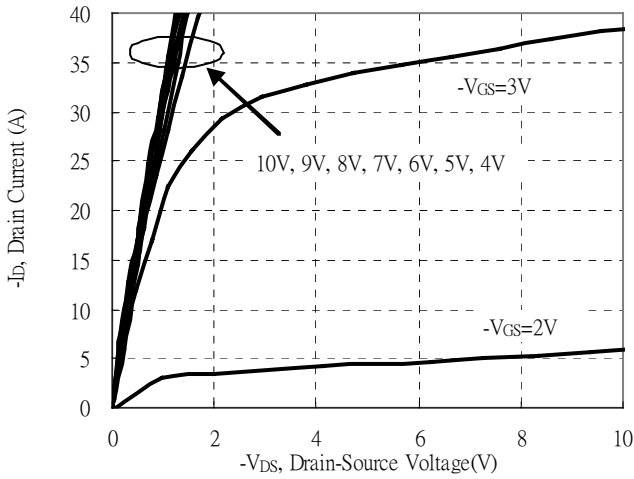


unit : mm

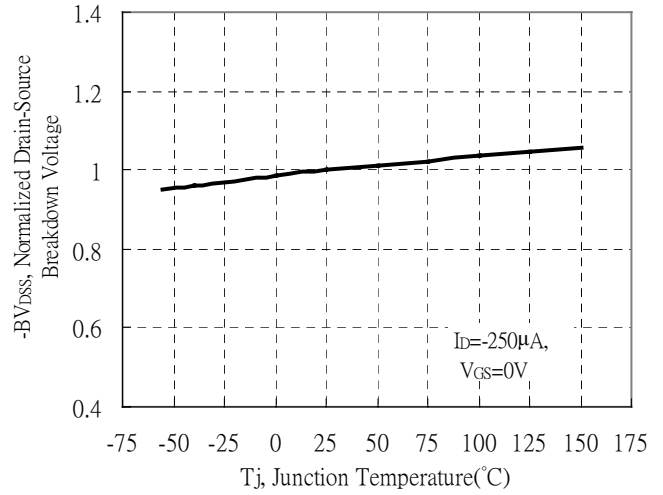


### Typical Characteristics

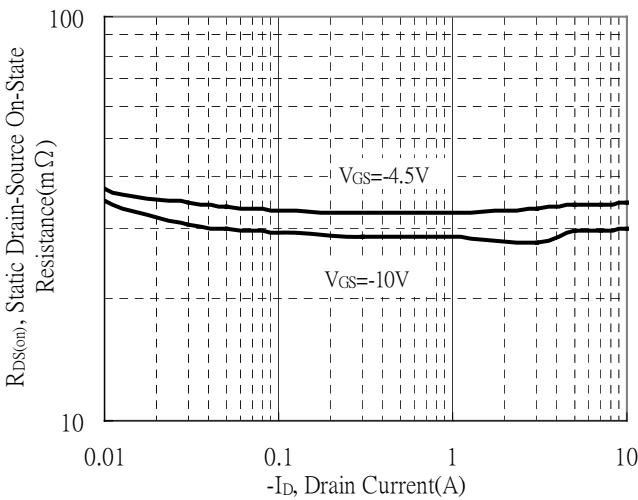
Typical Output Characteristics



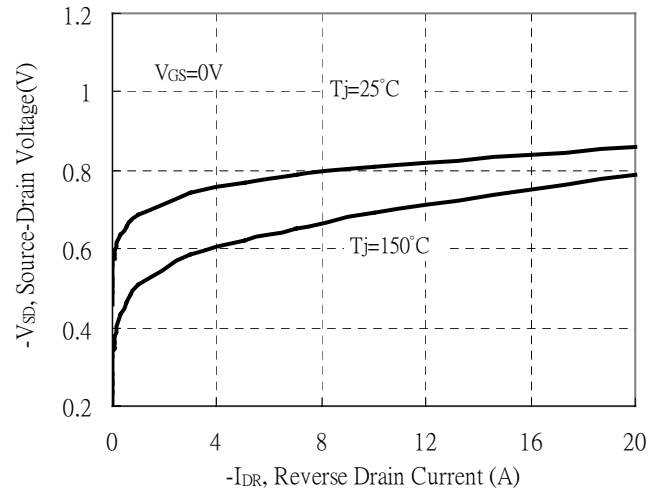
Brekdown Voltage vs Ambient Temperature



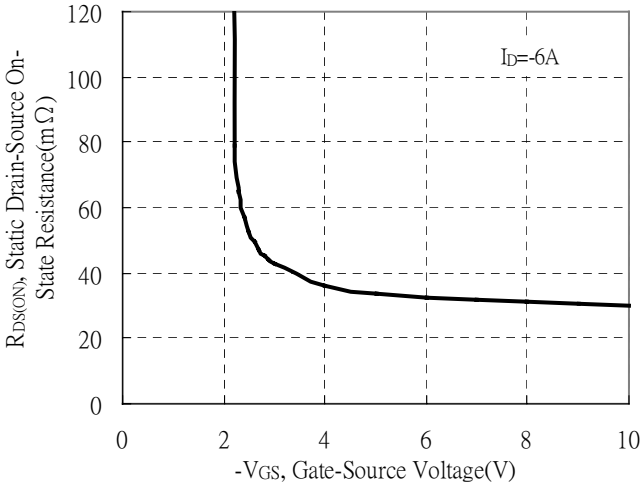
Static Drain-Source On-State resistance vs Drain Current



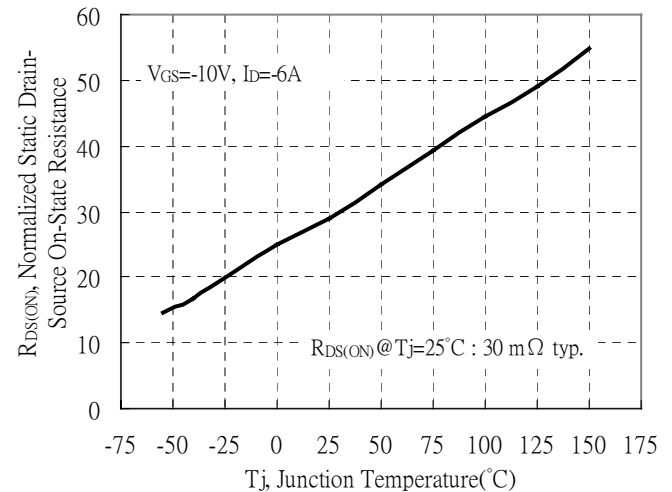
Reverse Drain Current vs Source-Drain Voltage



Static Drain-Source On-State Resistance vs Gate-Source Voltage

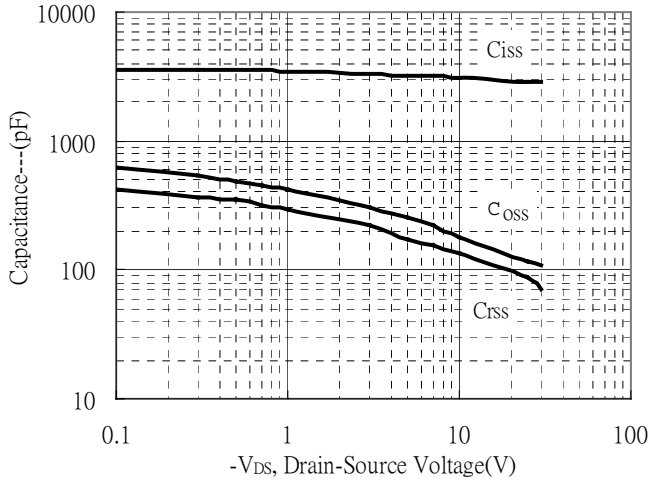


Drain-Source On-State Resistance vs Junction Temperature

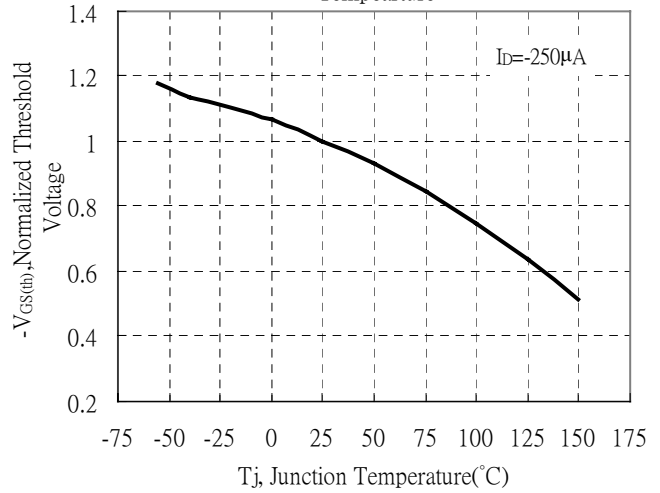


**Typical Characteristics(Cont.)**

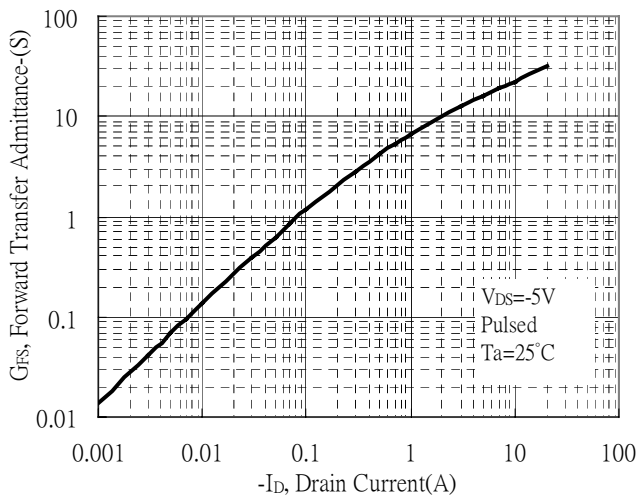
Capacitance vs Drain-to-Source Voltage



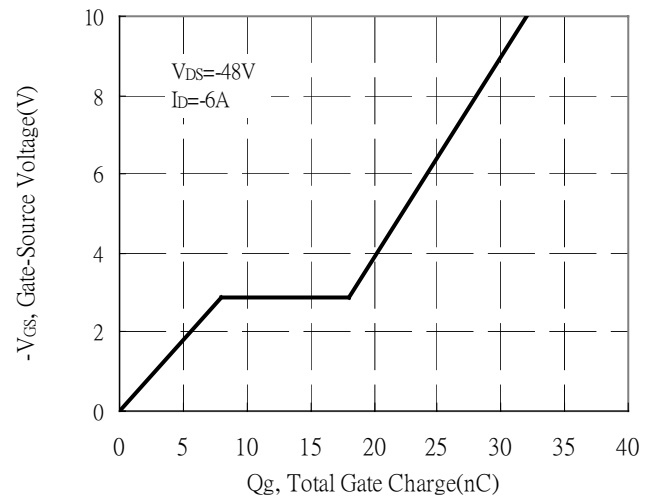
Normalized Threshold Voltage vs Junction Temperature



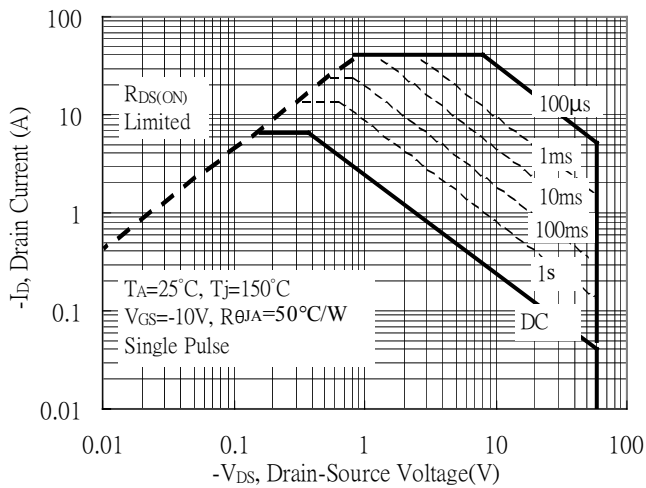
Forward Transfer Admittance vs Drain Current



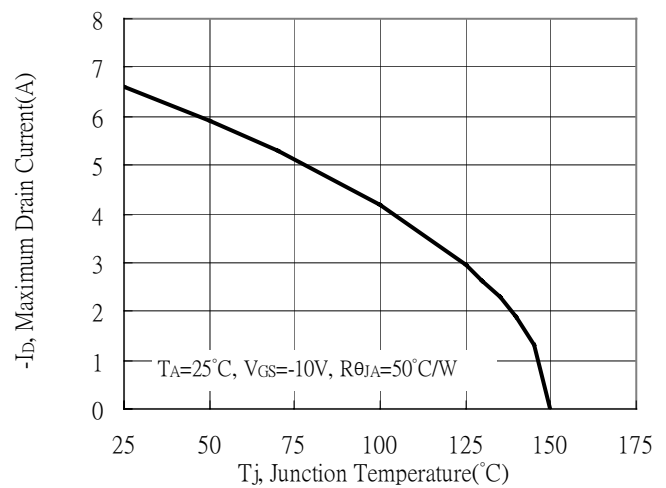
Gate Charge Characteristics



Maximum Safe Operating Area



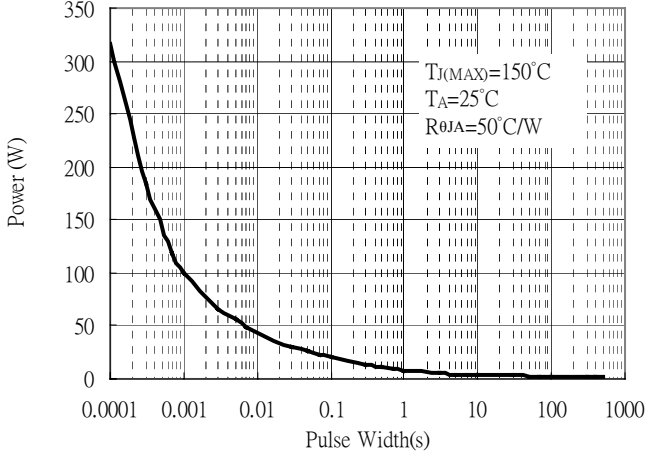
Maximum Drain Current vs Junction Temperature



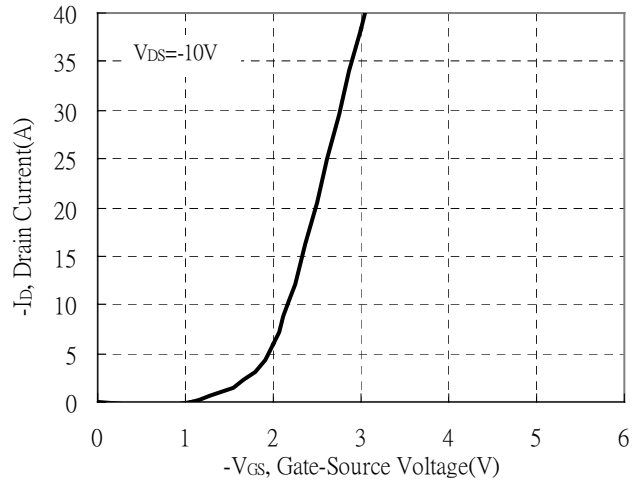


**Typical Characteristics(Cont.)**

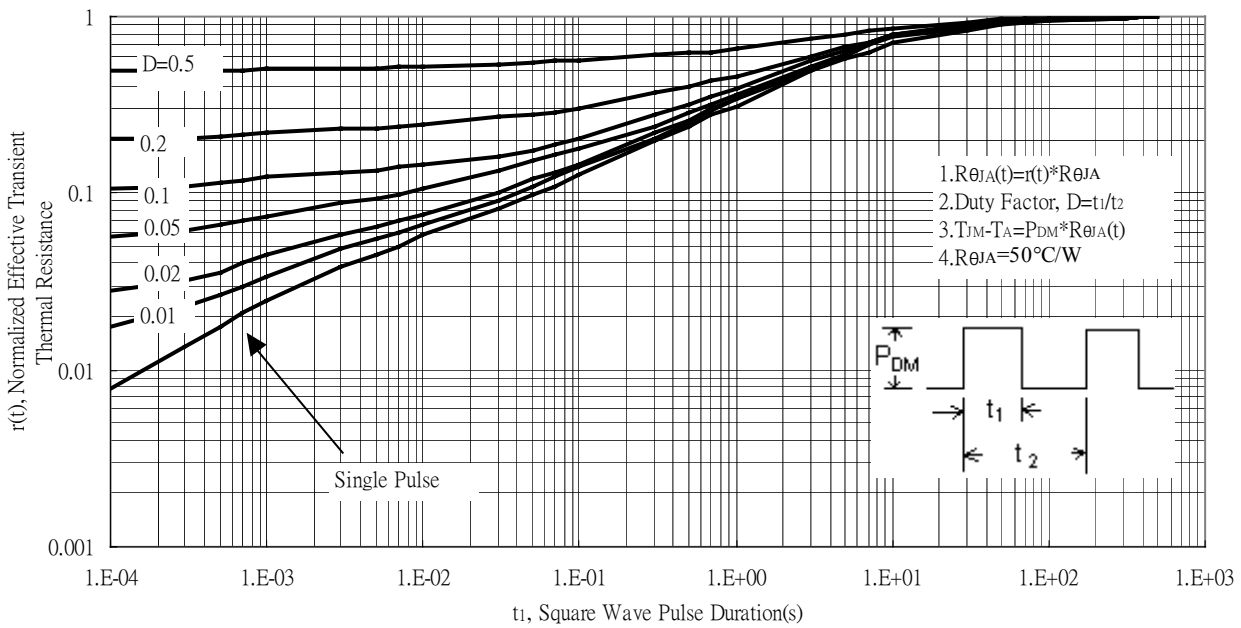
Single Pulse Power Rating, Junction to Ambient  
 (Note on page 2)



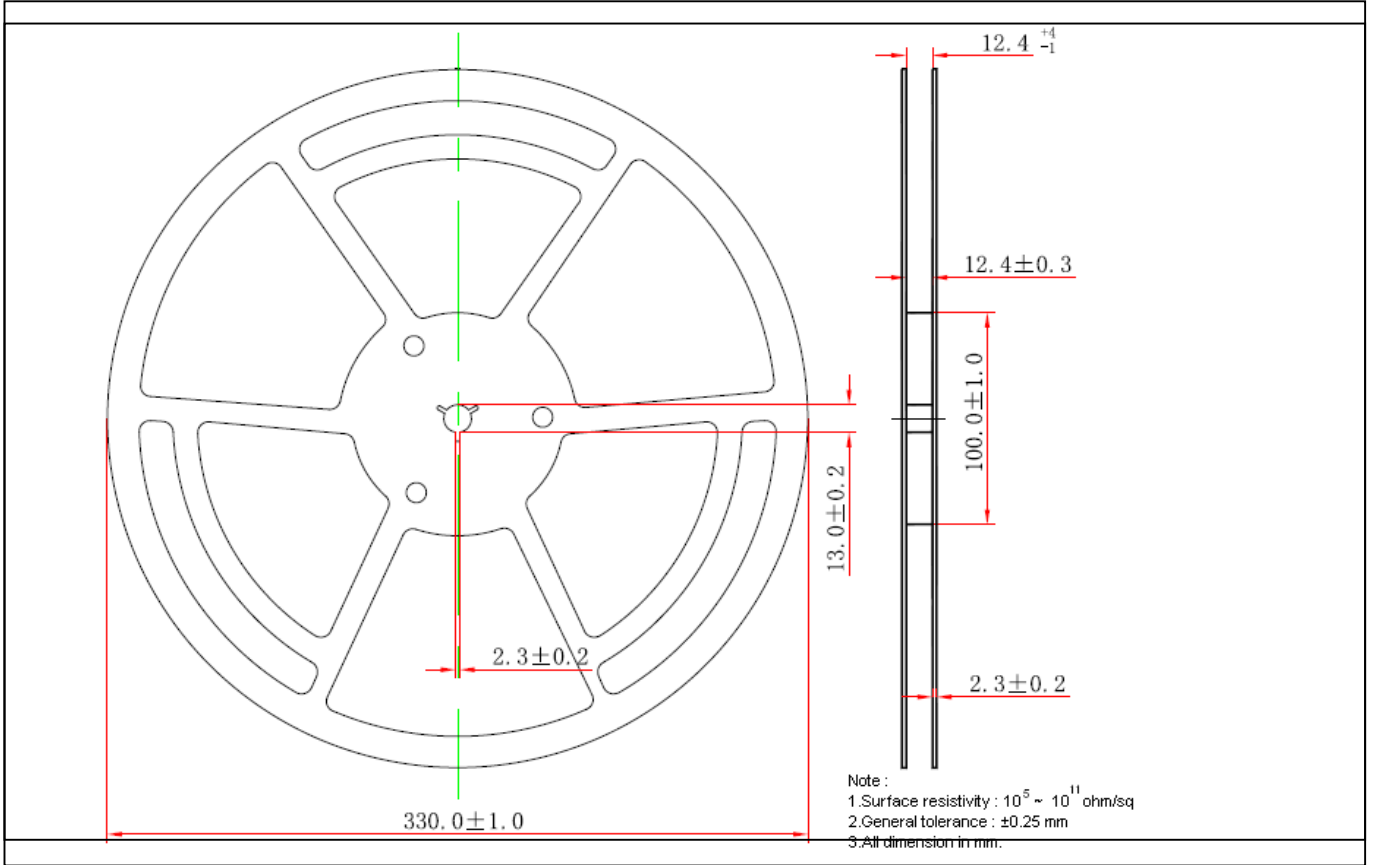
Typical Transfer Characteristics



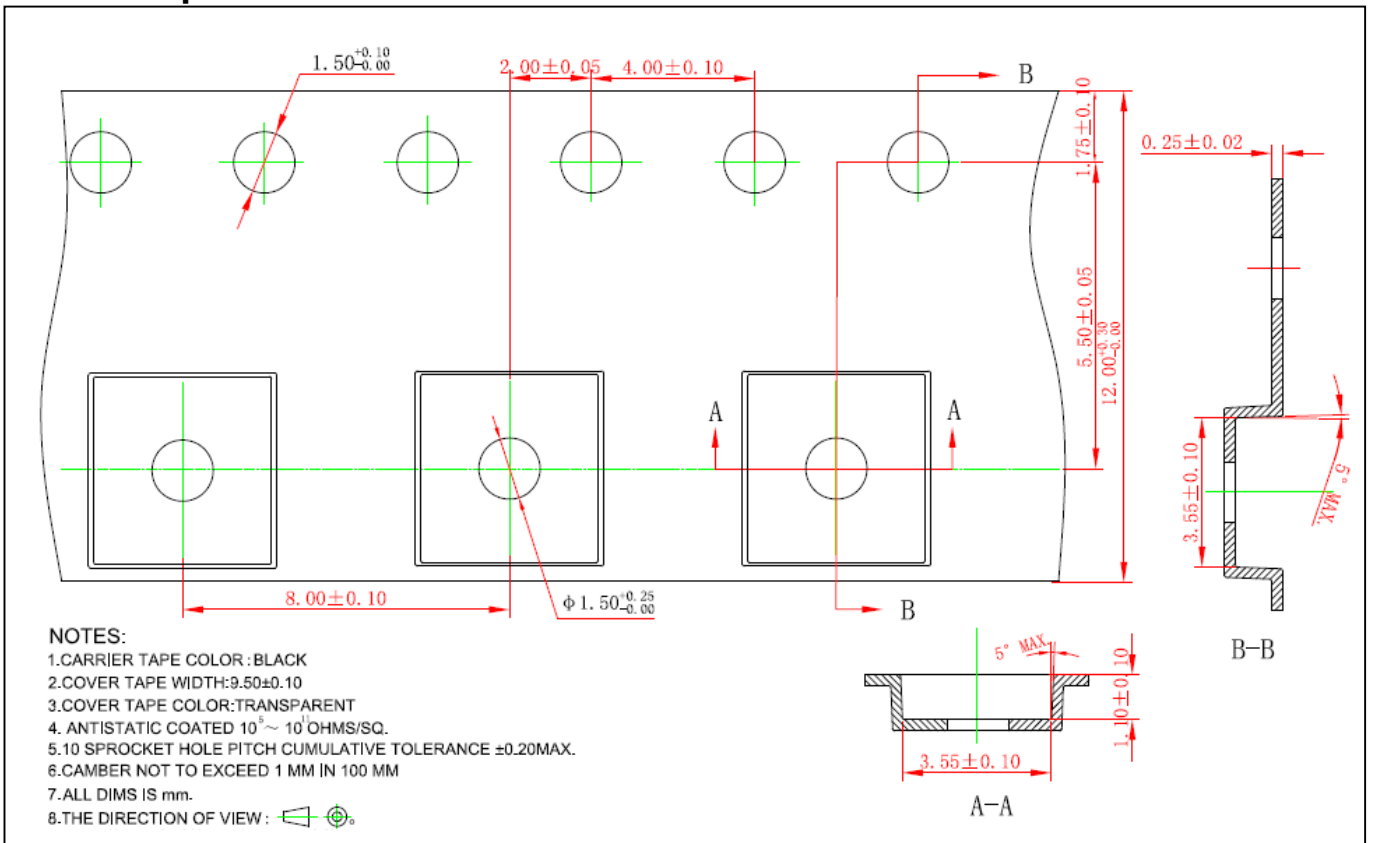
Transient Thermal Response Curves



**Reel Dimension**



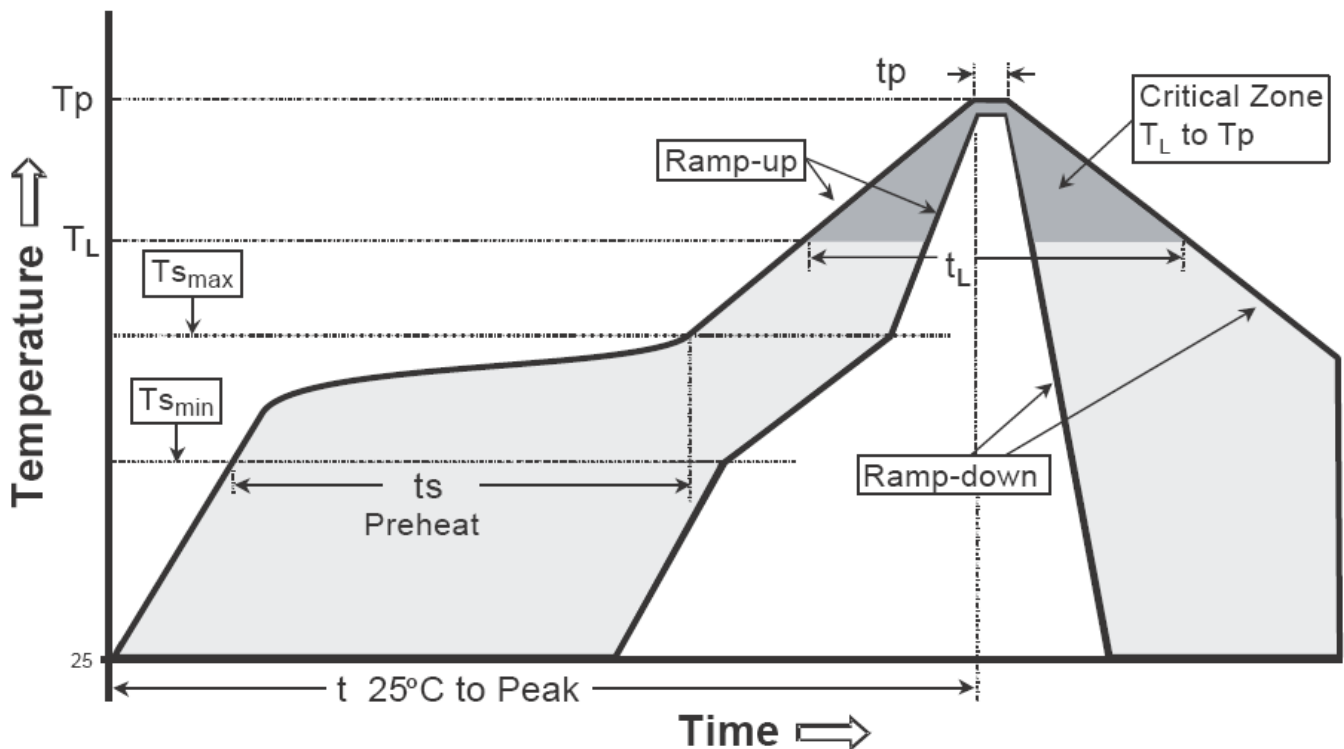
**Carrier Tape Dimension**



**Recommended wave soldering condition**

Product	Peak Temperature	Soldering Time
Pb-free devices	260 +0/-5 °C	5 +1/-1 seconds

**Recommended temperature profile for IR reflow**

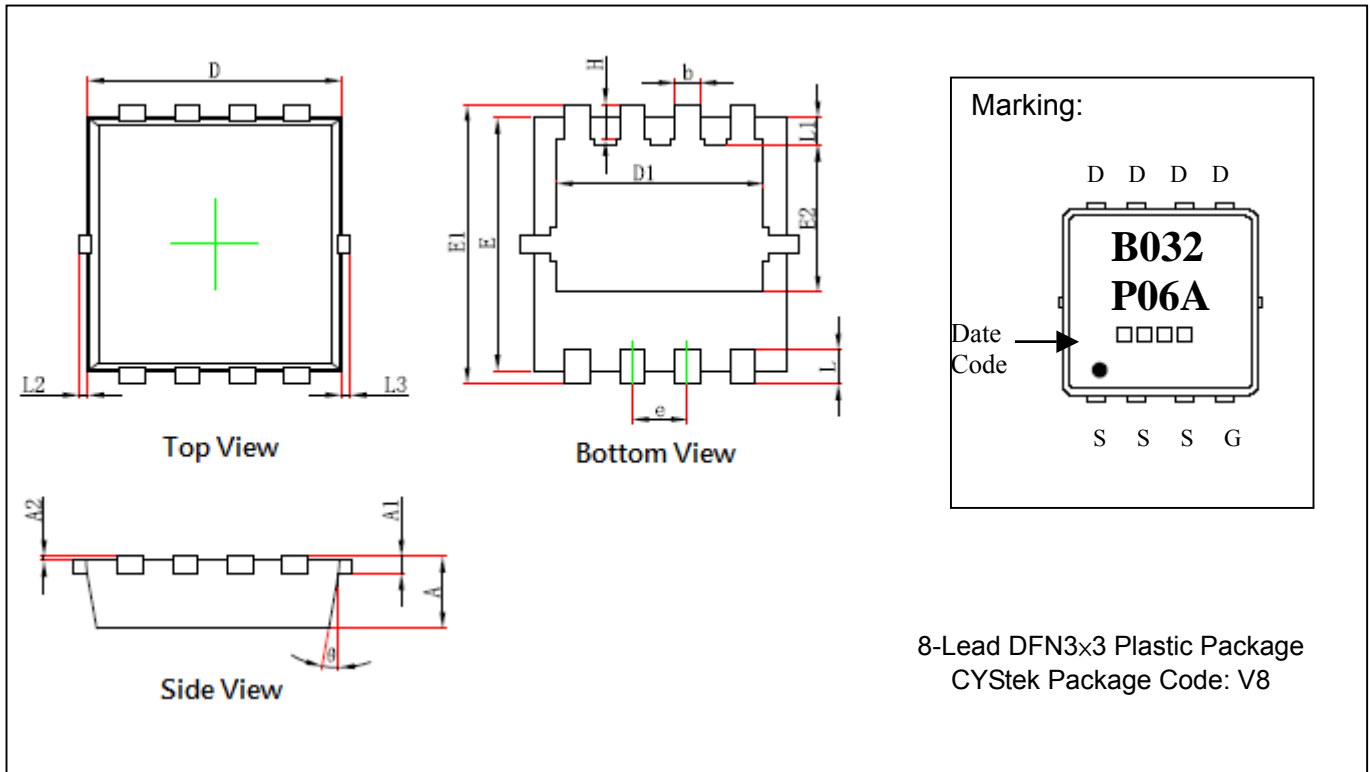


Profile feature	Sn-Pb eutectic Assembly	Pb-free Assembly
Average ramp-up rate (Tsmax to Tp)	3°C/second max.	3°C/second max.
Preheat		
-Temperature Min(Ts min)	100°C	150°C
-Temperature Max(Ts max)	150°C	200°C
-Time(ts min to ts max)	60-120 seconds	60-180 seconds
Time maintained above:		
-Temperature (T <sub>L</sub> )	183°C	217°C
- Time (t <sub>L</sub> )	60-150 seconds	60-150 seconds
Peak Temperature(T <sub>P</sub> )	240 +0/-5 °C	260 +0/-5 °C
Time within 5°C of actual peak temperature(tp)	10-30 seconds	20-40 seconds
Ramp down rate	6°C/second max.	6°C/second max.
Time 25 °C to peak temperature	6 minutes max.	8 minutes max.

Note : All temperatures refer to topside of the package, measured on the package body surface.



**DFN3x3 Dimension**



DIM	Inches		Millimeters		DIM	Inches		Millimeters	
	Min.	Max.	Min.	Max.		Min.	Max.	Min.	Max.
A	0.026	0.033	0.650	0.850	b	0.008	0.016	0.200	0.400
A1	0.006	REF	0.152	REF	e	0.022	0.030	0.550	0.750
A2	0.000	0.002	0.000	0.050	L	0.012	0.020	0.300	0.500
D	0.114	0.122	2.900	3.100	L1	0.007	0.019	0.180	0.480
D1	0.091	0.102	2.300	2.600	L2	0.000	0.004	0.000	0.100
E	0.114	0.122	2.900	3.100	L3	0.000	0.004	0.000	0.100
E1	0.124	0.136	3.150	3.450	H	0.012	0.020	0.315	0.515
E2	0.060	0.076	1.535	1.935	θ	9°	13°	9°	13°

**Notes:** 1.Controlling dimension: millimeters.  
 2.Maximum lead thickness includes lead finish thickness, and minimum lead thickness is the minimum thickness of base material.  
 3.If there is any question with packing specification or packing method, please contact your local CYStek sales office.

**Material:**

- Lead: pure tin plated.
- Mold Compound: Epoxy resin family, flammability solid burning class: UL94V-0.

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